## **DA3J102D**

## Silicon epitaxial planar type

For high speed switching circuits 2 elements anode-common type DA3X102D in SMini3 type package

#### ■ Features

- Short reverse recovery time t<sub>rr</sub>
- Low terminal capacitance C<sub>t</sub>
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

#### Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

## ■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter                                   | Symbol | Rating           | Unit        |    |  |
|---|--------|------------------|-------------|----|--|
| Reverse voltage                             |        | V <sub>R</sub>   | 80          | V  |  |
| Maximum peak reverse voltage                |        | V <sub>RM</sub>  | 80          | V  |  |
| Forward current                             | Single |                  | 100         | mA |  |
|   | Double | $I_{\rm F}$      | 150         | mA |  |
| Peak forward current                        | Single |                  | 225         | mA |  |
|   | Double | $I_{FM}$         | 340         | mA |  |
| Non-repetitive peak forward surge current * | Single |                  | 500         | mA |  |
|   | Double | I <sub>FSM</sub> | 750         | mA |  |
| Junction temperature                        |        | $T_j$            | 150         | °C |  |
| Storage temperature                         |        | T <sub>stg</sub> | -55 to +150 | °C |  |

#### ■ Package

Code

SMini3-F2-B

• Pin Name

1: Cathode-1 3: Anode-1 2: Cathode-2 Anode-2

#### ■ Marking Symbol: 23

#### ■ Internal Connection



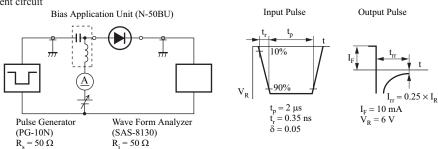
Note) \*: 1 t = 1 s

### ■ Electrical Characteristics $T_a = 25$ °C±3°C

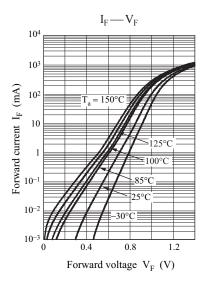
| Parameter               | Symbol          | Conditions   | Min | Тур | Max | Unit |
|-------------------------|-----------------|--|-----|-----|-----|------|
| Forward voltage         | V <sub>F</sub>  | $I_F = 100 \text{ mA}$   |     |     | 1.2 | V    |
| Reverse voltage         | V <sub>R</sub>  | $I_R = 100 \mu A$  | 80  |     |     | V    |
| Reverse current         | $I_R$           | $V_R = 80 V$   |     |     | 100 | nA   |
| Terminal capacitance    | Ct              | $V_R = 0 V, f = 1 MHz$   |     |     | 15  | pF   |
| Reverse recovery time * | t <sub>rr</sub> | $I_F = 10 \text{ mA}, V_R = 6 \text{ V}, I_{rr} = 0.25 \times I_R$ |     |     | 10  | ns   |

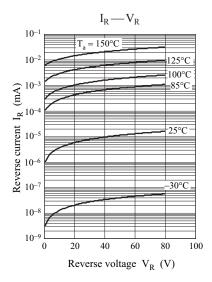
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

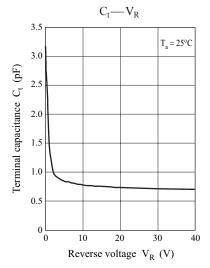
- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 100 MHz
  - \*: t<sub>rr</sub> measurement circuit



DA3J102D Panasonic



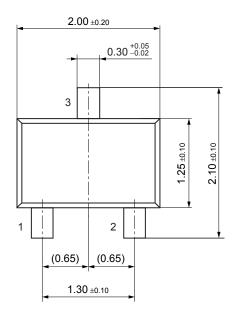


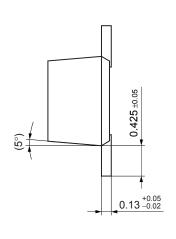


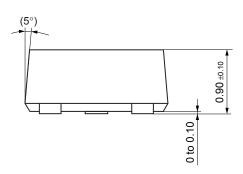
2 Ver. CED

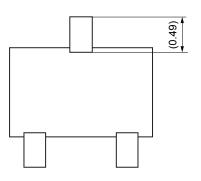
SMini3-F2-B

Unit: mm









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